

ENGINEERING DEPT.		PRODUCT SPECIFICATION For 1.27 mm (.050") Pin Header of System CH54	SPEC.NO.: SPCH035C
REVISIONS	ECNT120128		PAGE: 1/3

1. SCOPE:

This specification contains the test requirement of subject pin headers when tested under the condition and below standards base on CviLux test procedure

2. APPLICABLE STANDARDS:

MIL - STD - 202	Methods for test of connectors for electronic equipment
EIA - 364	Test methods for electrical connectors
JIS - C - 5402	Methods for test of connectors for electronic equipment
UL 94	Test for flammability of plastic materials for parts in devices and appliance
J-STD-020	Resistance to soldering Temperature for through hole Mounted Devices
SS-00254	Test methods for electronic components ,LEAD-FREE soldering Part design standards

3. APPLICABLE SERIES NO.: **CH54 Series**

4. SHAPE, CONSTRUCTION AND DIMENSIONS

See attached drawings

5. MATERIALS

See attached drawings

6. MATERIALS

(P.C. Board on which the Pin Header are installed), 0.8 mm (.031") ~ 1.6 mm (.063")



REVIEWED : Eisley APPROVED : Sun VERIFIED : Eric .

ENGINEERING DEPT.		PRODUCT SPECIFICATION For 1.27 mm (.050") Pin Header of System CH54	SPEC.NO.: SPCH035C
REVISIONS	ECNT120128		PAGE: 2/3

7. ELECTRICAL PERFORMANCE:

	ITEM	TEST CONDITION	REQUIREMENT
7.1	Rated current and voltage		1A 250V AC (r.m.s.)
7.2	Contact resistance	Dry circuit of DC 20 mV max. , 100 mA max	Less than 20 mΩ
7.3	Dielectric strength	When applied AC 600 V 1minute between adjacent terminal	No change
7.4	Insulation resistance	When applied DC 500 V between adjacent terminal or ground	More than 1000 MΩ

8. MECHANICAL PERFORMANCE:

	ITEM	TEST CONDITION	REQUIREMENT
8.1	Pin retention force	Push pin from insulator base at speed 25± 3 mm per minute	More than 200 gram

9. ENVIRONMENTAL PERFORMANCE:

	ITEM	TEST CONDITION	REQUIREMENT
9.1	Solder ability	Soldering time: 3 ± 0.5 second Soldering pot: 245 ± 5 °C	Minimum: 90% of immersed area
9.2	Resistance to soldering heat	DIP Type: Soldering time: 5 ± 0.5 second Soldering pot: 260 ± 5 °C SMT Type : Soldering time: 20 second Max. Soldering pot: 250~260 °C	No damage
9.3	Heat aging	105± 2 °C, 96 hours	No damage
9.4	Humidity	40± 2 °C, 90-95% RH, 96 hours measurement must be taken within 30 min. after tested	Appearance: No damage Contact resistance: Less than twice of initial Dielectric strength: To pass para 7-3
9.5	Temperature cycling	One cycle consists of : (1)-55 ⁺⁰ / ₋₃ °C , 30 min. (2)Room temp. 10-15 min. (3) 85 ⁺³ / ₋₀ °C , 30 min. (4)Room temp. 10-15 min.	Appearance: No damage Contact resistance: Less than twice of initial

ENGINEERING DEPT.		PRODUCT SPECIFICATION For 1.27 mm (.050") Pin Header of System CH54	SPEC.NO.: SPCH035C
REVISIONS	ECNT120128		PAGE: 3/3

ITEM	TEST CONDITION	REQUIREMENT
9.6 Salt spray	<p>Temperature: $35 \pm 3^{\circ}\text{C}$ Solution: $5 \pm 1\%$ Spray time: 48 ± 4 hours (Stamping before plated) Spray time: 24 ± 4 hours (Stamping after plated)</p> <p>Mate connectors and expose to the following salt mist conditions. Upon completion of the exposure period, salt deposits shall be removed by a gentle wash or dip in running water and dried naturally, after which the specified measurements shall be performed.</p> <p>The specimens shall be suspended from the top using waxed twine, string or nylon thread.</p> <p>The test only define the plating area, without plating area (as copper cross section) will not be defined.</p> <p>(EIA 364-26B / MIL-STD-202 Method 101)</p>	<p>Appearance: No damage Contact resistance: Less than twice of initial</p>

10. AMBIENT TEMPERATURE RANGE:

-40 to + 105 °C ; + 215 °C intermittent (Vapor Phase Solder Reflow) for SMT type

11. Recommended IR Reflow Temperature Profile:

